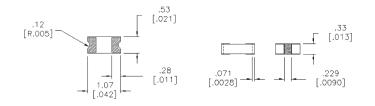
Product Dimensions: mm [inches]



Design Considerations

Solder Pad Recommendation: mm [inches]

2.20

0.70

device associated \ Lecond pad direct ours ours ours cent pad direct cent pad direct ours cen The location in the circuit for the MLP family has to be carefully determined. For better performing, the device should be placed as close to the signal input as possible and ahead of any other component. Due to the high carrent associated with an ESD event, it is recommended to use a "0-stub" pad design (pad directly on the signal/data line and second pad directly mn on ground).

Environmental Specifications:

- Load Humidity: 12VDC per EIA/IS-772 Para. 4.4.2, +85°C, 85% RH for 1000 hours
- Thermal Shock: EIA/IS-722 Para 4.6, Air to Air -55°C to +125°C, 5 cycles
- Moisture Resistance Test: MIL-STD-202G Method 106G, 10 vc es
- Mechanical Shock: EIA/IS-722 Para. 4.9
- Vibration: EIA/IS-722 Para. 4.10
- · Resistance to Solvent: EIA/IS-722 Para. 4.11
- Operating & Storage Temperature Range: -55°C

Soldering Recommendations

- · Compatible with lead and lead-free solder reliow proce ses
- · Peak reflow temperatures and durations:
 - IR Reflow = 260°C max for 10 sec. mnx
 - Wave Solder = 260°C max. for 10 sec. max
- Recommended IR Reflow Profile:

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